

DECLARATION

As a below-named inventor, I hereby declare that:

My correct residence, post office address and citizenship are stated below next to my name.

I believe myself to be the original, first and sole inventor (if only one name is listed below) or an original and first joint inventor (if more than one name is listed below) of the subject matter which is disclosed and claimed and for which a patent is sought on the invention entitled:

Semi-conductor mounting apparatus with a chip gripper travelling back and forth

The specification of this subject matter:

- ☐ is attached hereto.
- ☐ was filed on _____;
- ☐ was assigned serial No. _____;
- ☐ which was amended on _____.

I hereby state that I have reviewed and understand the contents of the above identified patent application, including the claims, as amended by any amendment(s) referred to above. I believe the subject matter claimed in the above-identified application to be new and to be unobvious to persons of ordinary skill in the art in view of the prior art of which I am aware. I further hereby state that the specification of the above identified patent application adequately describes how to make and use the claimed invention, and further that it sets forth the best mode for practicing the invention known to me as of the date that the application was filed. I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 C.F.R. §1.56(a).

I hereby claim foreign priority benefits under 35 U.S.C. §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Application No.	Country	Filing Date	Priority Claimed
1997 2807/97	CH	December 07, 1997	

I hereby claim the benefit under 35 U.S.C. §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in these prior United States application(s) in the manner provided by 35 U.S.C. §112, I acknowledge the duty to disclose material information as defined in 37 C.F.R. §1.56(a) which occurred between the filing date of the prior application(s) and the national or PCT international filing date of this application.

Application No.	Filing Date	Status (Issued, Pending, Abandoned)

FULL NAME OF INVENTOR 1	FIRST Name Samuel	MIDDLE Initial(s)	LAST Name Schindler
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RESIDENCE AND CITIZENSHIP	City	State or Foreign Country	Country of Citizenship CH
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POST OFFICE ADDRESS	Number and Street Löwengasse 27	City Horgen	State or Country CH	Zip Code 8810
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FULL NAME OF INVENTOR 2	FIRST Name	MIDDLE Initial(s)	LAST Name
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RESIDENCE AND CITIZENSHIP	City	State or Foreign Country	Country of Citizenship
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POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
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FULL NAME OF INVENTOR 3	FIRST Name	MIDDLE Initial(s)	LAST Name
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RESIDENCE AND CITIZENSHIP	City	State or Foreign Country	Country of Citizenship
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POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
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FULL NAME OF INVENTOR 4	FIRST Name	MIDDLE Initial(s)	LAST Name
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RESIDENCE AND CITIZENSHIP	City	State or Foreign Country	Country of Citizenship
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POST OFFICE ADDRESS	Number and Street	City	State or Country	Zip Code
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I further declare that all statements made herein of my own knowledge are true and that all statements made upon information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.



22. OCT. 1998

Signature of Inventor 1

Date

Signature of Inventor 2

Date

Signature of Inventor 3

Date

Signature of Inventor 4

Date

POWER OF ATTORNEY

ESEC SA, a corporation organized in
Switzerland, assignee of the application for United States

Letters Patent for an invention entitled:

Semi-conductor mounting apparatus with a chip gripper travelling back and forth

invented by: Samuel Schindler

- ☐ executed on even date herewith, or
- ☐ having serial No. _____, filed _____, 199____,

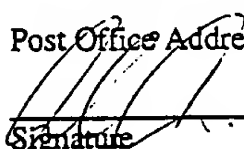
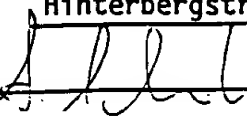
do(es) hereby appoint Kenneth D'Alessandro, Registration No. 29,144, David B. Ritchie, Registration No. 31,562, Jonathan H. Schafer, Registration No. 36,915, Steven J. Robbins, Registration No. 40,299, Stephen R. Uriarte, Registration No. 40,854, Powell L. Sprunger, Registration No. 26,239, Sean P. Lewis, Registration No. P42,798, Elise R. Heilbrunn, Registration No. P42,649, and Marc S. Hanish, Registration No. P42,626 as attorneys of record with full power of substitution and revocation, to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith, and certifies that it is the assignee of the entire right, title and interest in the patent application identified above by virtue of an assignment, a copy of which is attached, from the inventor(s) of the patent application identified above.

Please send all correspondence and direct all telephone calls to:

D'Alessandro & Ritchie
P.O. Box 640640
San Jose, CA 95164-0640
Telephone (408)-441-1100; Fax (408)-441-8400

The undersigned has reviewed all the documents in the chain of title of the patent application identified above and, to the best of undersigned's knowledge and belief, title is in the assignee identified above.

I, the undersigned, declare that I am the (an) assignee of the above identified application, or, if the assignee is a corporation, partnership, or other association, I am authorized to make this appointment on behalf of the assignee and I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing therefrom.

Full Assignee Name	<u>ESEC SA</u>	
Post Office Address	<u>Hinterbergstr. 32, CH-6330 Cham</u>	
Signature		<u>November 9, 1998</u>
		<u>Date</u>
<u>Silvia Duss</u>	<u>Erwin Schibig</u>	<u>Vice Presidents</u>
Print Name		Title

ASSIGNMENT

WHEREAS, I, SCHINDLER Samuel, a citizen of Switzerland, residing at Löwengasse 27, CH-8810 Horgen have invented a "Semi-conductor mounting apparatus with a chip gripper travelling back and forth" for which I execute application papers for a U.S. patent thereon which is filed at even date;

WHEREAS, ESEC SA, a Swiss corporation, having a place of business at Hinterbergstr. 32, CH-6330 Cham/Switzerland, is desirous of acquiring the exclusive right, title and interest in and to said invention and in and to the Letters Patent to be granted and issued therefor in the United States of America and its territories and possessions, and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby acknowledged, we do sell, assign, transfer and set over unto said ESEC SA, its successors and assigns, the full and exclusive right, title and interest in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America and its territories and possessions, but also for, to and in all other countries including all priority rights under the International Convention; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said ESEC SA, its successors and assigns, in accordance with this Assignment.

WITNESS OUR HAND at Cham, this 20th day of Oktober, 1998.


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